Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

| 1. (| Currently Amended) A substrate processing apparatus, comprising: |
|---|--|
| a | substrate holder capable of holding plural substrates; |
| a | processing chamber which houses the substrates held by the substrate holder; |
| and | |
| a | heater which heats the processing chamber; |
| W | wherein the substrate holder includes: |
| _ | at least three support columns provided substantially vertically; |
| _ | plural substrate mounting portions which mount the plural substrates |
| substantially horizontally at a predetermined interval, the substrate mounting portions being | |
| provided at multi-stages on the support columns so as to protrude from the support columns; | |
| _ | plural ring-like plates which surround the at least three support |
| columns, are provided at multi-stages on the support columns, and are provided substantially | |
| horizontally at a | predetermined interval with respect to the substrates supported on the |
| substrate mounting portions; and | |
| _ | notches which are formed by notching inner circumferential surfaces of |
| the ring-like plat | tes, the inner circumferential surfaces being opposite to the support columns, |
| are notched on a periphery of the support-columns, columns, the support columns being fitted | |
| into the notches. | |

2. (Previously Presented) The substrate processing apparatus according to claim 1, wherein the substrate mounting portions are columnar shape or approximately semi-columnar shape.

- 3. (Original) The substrate processing apparatus according to claim 2, wherein the substrate mounting portions are inclined downward toward an inside of the ring-like plates in a diameter direction.
 - 4-5. (Canceled)
- 6. (Previously Presented) The substrate processing apparatus according to claim 2, wherein tips of the substrate mounting portions are rounded or chamfered.
 - 7. (Canceled)
- 8. (Previously Presented) The substrate processing apparatus according to claim 1, wherein the support columns are composed into an approximately semi-columnar shape, and the substrate mounting portions are protruded on a chord side of the support columns.
- 9. (Original) The substrate processing apparatus according to claim 8, wherein, on the chord side, an inside thereof in a diameter direction of the ring-like plates is scooped out.
 - 10. (Canceled)

and

11. (Currently Amended) A substrate processing apparatus, comprising:a substrate holder capable of holding plural substrates;a processing chamber which houses the substrates held by the substrate holder;

a heater which heats the processing chamber;

wherein the substrate holder includes:

____at least three support columns provided substantially vertically; and ____plural ring-like plates which surround the at least three support

columns, are provided at multi-stages on the support columns, and are provided substantially

horizontally at a predetermined interval with respect to the substrates held by the substrate holder, holder; and

notches which are formed by notching inner circumferential surfaces of the ring-like plates, the inner circumferential surfaces being opposite to the support columns, are notched on a periphery of the support columns, columns, the support columns being fitted into the notches.

- 12. (Previously Presented) The substrate processing apparatus according to claim 11, wherein the support columns are composed into an approximately semi-columnar shape, and the substrate mounting portions are protruded on a chord side of the support columns.
 - 13. (Canceled)
- 14. (Original) The substrate processing apparatus according to claim 12, wherein, on the chord side, an inside thereof in a diameter direction of the ring-like plates is scooped out.
- 15. (Currently Amended) A substrate holder capable of holding plural substrates, comprising:

at least three support columns provided substantially vertically;

plural substrate mounting portions which mount the plural substrates substantially horizontally at a predetermined interval, the substrate mounting portions being provided at multi-stages on the support columns, so as to protrude from the support columns; and

plural ring-like plates which surround the at least three support columns, are provided at multi-stages on the support columns, and provided substantially horizontally at a predetermined interval with respect to the substrates supported on the substrate mounting portions,

wherein <u>notches</u> are formed by <u>notching</u> inner circumferential surfaces of the ring-like plates, the inner circumferential surfaces being opposite to the support columns, are notched on a periphery of the support columns, and the support columns are fitted into the notches.

- 16. (Canceled)
- 17. (Currently Amended) A substrate holder capable of holding plural substrates, comprising:

at least three support columns provided substantially vertically; and
plural ring-like plates which surround the at least three support columns, are
provided at multi-stages on the support columns, and are provided substantially horizontally
at a predetermined interval with respect to the substrates held by the substrate holder,

wherein <u>notches</u> are formed by notching inner circumferential surfaces of the ring-like plates, the inner circumferential surfaces being opposite to the support columns, are notched on a periphery of the support columns, and the support columns are fitted into the notches.

18. (Currently Amended) A method of manufacturing a semiconductor device, the method using a substrate processing apparatus including: a substrate holder capable of holding plural substrates; a processing chamber which houses the substrates held by the substrate holder; ha heater a heater which heats the processing chamber; and a gas supply pipe which supplies processing gas to the processing chamber heated by the heater, thereby processing the substrate, wherein the substrate holder includes: at least three support columns provided substantially vertically; plural substrate mounting portions which mount the plural substrates substantially horizontally at a predetermined interval, the substrate mounting portions being provided at multi-stages on the support columns so as to protrude from the support columns; and plural ring-like plates which surround the at least three support

columns, are provided at multi-stages on the support columns, and are provided substantially horizontally at a predetermined interval with respect to the substrates supported on the substrate mounting portions; and notches which are formed by notching inner circumferential surfaces of the ring-like plates, the inner circumferential surfaces being opposite to the support columns, are notehed on a periphery of the support columns, and the support columns are being fitted into the notches, the method comprising:

______mounting the substrates on the substrate mounting portions of the substrate holder;

______carrying the substrates mounted on the substrate mounting portions of the substrate holder into the processing chamber;

_____heating the processing chamber by the heater; and

_____supplying the processing gas to the heated processing chamber by the gas supply pipe, thereby processing the substrate.

- 19. (Previously Presented) The substrate processing apparatus according to claim 1, wherein an open width of the notch is larger than a width of the substrate mounting portion.
- 20. (Previously Presented) The substrate processing apparatus according to claim 1, wherein an open width of the notch is larger than an outside diameter of the support columns.
- 21. (Previously Presented) The substrate processing apparatus according to claim 1, wherein the notch comprises:

a fitting portion as a hole into which the support columns is fitted; and an opening which opens the fitting portion to the inner circumferential direction of the ring-like plate.

- 22. (Previously Presented) The substrate processing apparatus according to claim 11, wherein an open width of the notch is larger than an outside diameter of a corresponding support column.
- 23. (Previously Presented) The substrate processing apparatus according to claim 11, wherein the notch comprises:
- a fitting portion as a hole into which the support columns is fitted; and an opening which opens the fitting portion to the inner circumferential direction of the ring-like plate.
- 24. (Previously Presented) The substrate processing apparatus according to claim 15, wherein an open width of the notch is larger than a width of the substrate mounting portion.
- 25. (Previously Presented) The substrate processing apparatus according to claim 15, wherein an open width of the notch is larger than an outside diameter of a corresponding support column.
- 26. (Previously Presented) The substrate processing apparatus according to claim 15, wherein the notch comprises:
- a fitting portion as a hole into which a corresponding support column is fitted; and
- an opening which opens the fitting portion to the inner circumferential direction of the ring-like plate.
 - 27. (Canceled)
- 28. (New) The substrate holder according to claim 15, wherein the support columns are composed into an approximately semi-columnar shape, and the substrate mounting portions are protruded on a chord side of the support columns.

29. (New) The substrate holder according to claim 28, wherein, on the chord side, an inside thereof in a diameter direction of the ring-like plates is fretted.